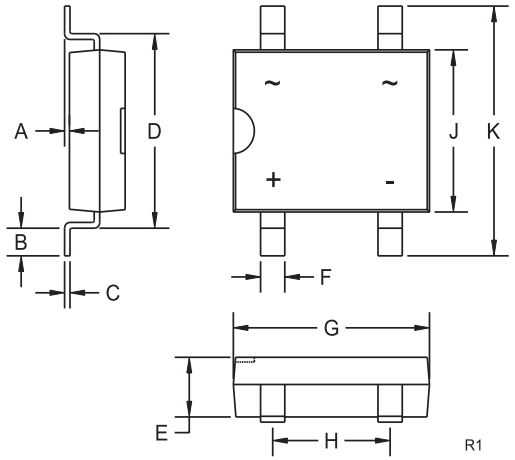
Package Details
SMDIP Case

Mechanical Drawing

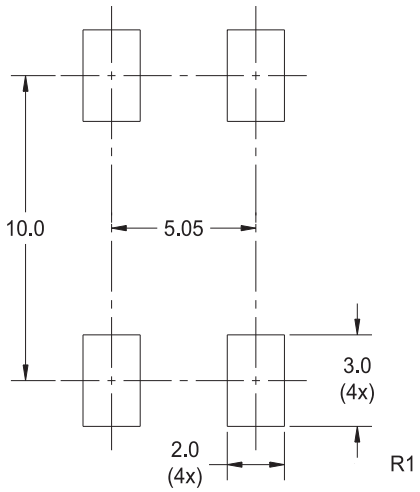


DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.004	0.008	0.10	0.20
B	0.040	0.060	1.02	1.52
C	0.009		0.23	
D	0.290	0.310	7.37	7.87
E	0.086	0.098	2.18	2.49
F	0.038	0.042	0.97	1.07
G	0.316	0.335	8.03	8.51
H	0.195	0.205	4.95	5.21
J	0.245	0.255	6.22	6.48
K	0.360	0.410	9.14	10.41

SMDIP (REV: R1)

Part Marking: Full Part Number

Mounting Pad Geometry (Dimensions in mm)

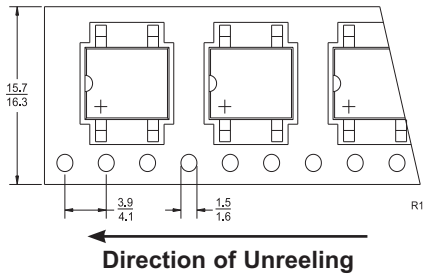


R2 (4-March 2010)

Package Details
SMDIP Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 16mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-2-A

Packaging Base

13” Reel = 1,000 pcs.
Bulk (per sleeve) = 50 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13”	4	4,000	15x4x15	38x10x38	8	4
	9	9,000	15x15x9	38x38x23	17	8
	18	18,000	15x15x18	38x38x46	33	15

Sleeve Packing Information

	Sleeves per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
	100	5,000	25x5x3	64x13x8	7	4
	200	10,000	25x5x7	64x13x18	14	7

Ordering Information

- For devices taped and reeled on 13” reels, add TR13 suffix to part number.
- For devices bulk packed in sleeves, add BK suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R2 (4-March 2010)

Material Composition Specification

SMDIP Case

Device average mass . . . . . **300 mg**

Fluctuation margin . . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.2%	3.6	Si	7440-21-3	1.2%	3.6	12,000
leadframe	copper	21.21%	63.63	Cu	7440-50-8	21.21%	63.63	212,099
die attach	high temperature solder paste	0.86%	2.6	Pb	7439-92-1	0.8%	2.4	8,000
				Sn	7440-31-5	0.04%	0.13	433
				Ag	7440-22-4	0.02%	0.07	217
encapsulation*	EMC	74.39%	223.18	silica	7631-86-9	50.59%	151.76	505,858
				epoxy resin	29690-82-2	14.88%	44.64	148,789
				phenol resin	9003-35-4	7.44%	22.32	74,393
				Sb_2O_3	1309-64-4	0.74%	2.23	7,439
				Br	7726-95-6	0.74%	2.23	7,439
	EMC GREEN	74.39%	223.18	silica (fused)	60676-86-0	57.28%	171.85	572,821
				epoxy resin	29690-82-2	7.44%	22.32	74,392
				phenol resin	9003-35-4	7.22%	21.65	72,160
				carbon black	1333-86-4	0.22%	0.67	2,231
				metal hydroxide	1309-42-8	2.23%	6.69	22,315
plating**	tin/lead process	2.33%	7.0	Sn	7440-31-5	1.87%	5.6	18,666
				Pb	7439-92-1	0.47%	1.4	4,667
	matte tin	2.33%	7.0	Sn	7440-31-5	2.33%	7.0	23,333

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.